

IN THE ABSTRACT:

Please amend the Abstract as follows:

[The present invention relates to probe] Probe cards are configured with protective circuitry suitable for use in electrical testing of semiconductor dice without damage to the probe cards. [In preferred embodiments of the invention, protective] Protective fuses are provided in electrical communication with conductive traces and probe elements (e.g., probe needles) of a probe card. The fuses may be active or passive fuses and are preferably self-resetting, repairable, and/or replaceable. Typically, the fuses will be interposed in, or located adjacent to, conductive traces residing over a surface of the probe card. [In this regard, methods] Methods of fabricating a probe card are provided, as well as various probe card configurations. A semiconductor die testing system using the probe card [of the present invention] is also provided.

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